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6-27-02
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PATENT

Customer No. 22,852

Attorney Docket No. 04329.2270-01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re 53(b) Continuation Application of:)
)
Shinsuke SAKAMOTO et al.) Group Art Unit: 2815
)
Application No.: 09/527,563) Examiner: E. Lee
)
Filed: March 16, 2000)
)
For: SEMICONDUCTOR)
INTEGRATED CIRCUIT DEVICE)
AND WIRING ARRANGING)
METHOD THEREOF)

Assistant Commissioner for Patents
Washington, DC 20231

Sir:

PRELIMINARY AMENDMENT

Prior to the examination of the above application, please amend this application
as follows:

IN THE SPECIFICATION:

Please amend the specification as follows:

On page 1, replace the paragraph beginning on line 11 with the following:

A1

The present invention relates to a semiconductor integrated circuit device making
use of an area pad and a wiring arranging method thereof.

On page 9, replace the paragraph beginning on line 22 with the following:

As described above, the wiring length of the I/O slot can be shortened by the
rewiring 24, 33 on the outermost periphery of the chip, and the delay in the signal

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